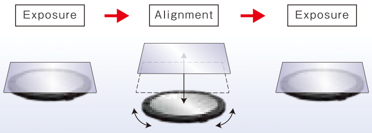
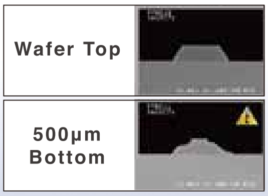
Applying Light to Life

# UX-4

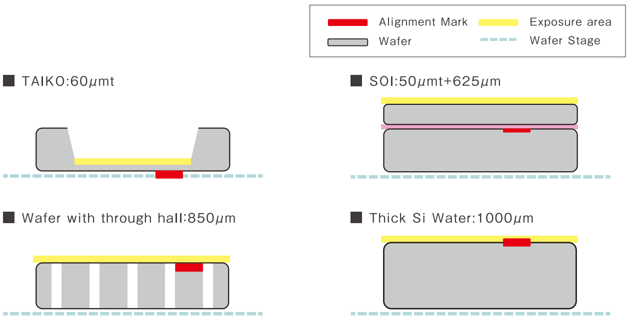
## Full-Field Projection Aligner

| | |
|---|---|
| Resolution | 2μm L/S~ |
| Overlay | Top Side : ±1μm, Back Side : ±1.5μm |
| Throughput | 120wph |
| Wafer Size | Φ100mm / 150mm / 200mm |
| | Si, Sapphire, GaN, GaAs, |
| Wafer Transfer | Cassette to Cassette Automatic |

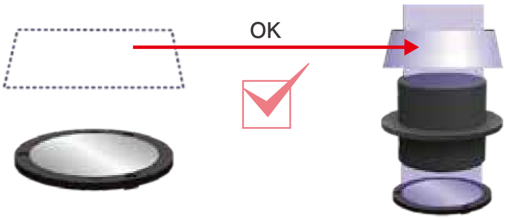
## Advantage of Full-Field Projection Lithography

| | UX-4(Full-Field Projection) | Proximity/Contact Aligner |
|---|---|---|
| Mask Damage Free |  ✓ No mask-wafer contact throughout the process. | ✗  |
| High Productivity |  ✓ Full-Field Projection > Proximity/Contact Aligner | ✗  |
| 3D Lithography |  ✓ Large Depth of Focus. High resolution on both top and bottom of step. | ✗  |
| Thick Resist Process |  ✓ No mask-wafer sticking problem with thick-sticky resist. | ✗  |

### Flexibility on wafer format



### Mask Compatibility



Use your own contact aligner mask.
No special mask needed.

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